

IN THE CLAIMS:

Claims 1-24 have been amended herein. All of the pending claims 1 through 24 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) An assembly for mounting a semiconductor device to a carrier substrate, comprising:  
an alignment device with at least one receptacle formed therein; and  
at least one semiconductor device including a mounting element with a receptacle configured to receive at least a portion of ~~said~~ the at least one semiconductor device in nonparallel orientation relative to a carrier substrate.

2. (Currently Amended) The assembly of claim 1, wherein ~~said~~ the at least one semiconductor device includes at least one contact pad adjacent a single edge thereof.

3. (Currently Amended) The assembly of claim 2, wherein ~~said~~ the alignment device comprises at least one contact located so as to be aligned with ~~said~~ the at least one contact pad of ~~said~~ the at least one semiconductor device upon interconnection thereof with ~~said~~ the alignment device.

4. (Currently Amended) The assembly of claim 3, wherein, upon interconnection of ~~said~~ the at least one semiconductor device with ~~said~~ the alignment device, ~~said~~ the at least one contact resiliently abuts ~~said~~ the at least one contact pad to establish an electrically conductive connection therebetween ~~between said at least one contact and said at least one contact pad~~.

5. (Currently Amended) The assembly of claim 2, wherein ~~said~~ the at least one semiconductor device comprises a semiconductor die and ~~said~~ the at least one contact pad comprises a bond pad of ~~said~~ the semiconductor die.

6. (Currently Amended) The assembly of claim 1, wherein ~~said~~ the alignment device is configured to engage or to be engaged by ~~said~~ the mounting element.

7. (Currently Amended) The assembly of claim 6, wherein ~~said~~ the alignment device includes an actuator for adjusting ~~said~~ the alignment device between an engagement state and a nonengagement state.

8. (Currently Amended) The assembly of claim 1, wherein ~~said~~ the alignment device includes a plurality of interconnection receptacles formed therein.

9. (Currently Amended) The assembly of claim 1, wherein ~~said~~ the at least one semiconductor device includes a retainer having at least one receptacle configured to receive and secure an edge of ~~said~~ the at least one semiconductor device.

10. (Currently Amended) A user-upgradable semiconductor device assembly, comprising:  
at least one semiconductor device including a mounting element; and  
an alignment device including at least one receptacle configured to receive at least an edge of ~~said~~ the at least one semiconductor device with ~~said~~ the at least one semiconductor device being oriented nonparallel to a carrier substrate.

11. (Currently Amended) The user-upgradable semiconductor device assembly of claim 10, wherein ~~said~~ the alignment device is configured to engage or to be engaged by ~~said~~ the mounting element.

12. (Currently Amended) The user-upgradable semiconductor device assembly of claim 10, wherein ~~said~~ the alignment device includes an actuator positionable between a mounting element-engagement state and a mounting element-nonengagement state.

13. (Currently Amended) The user-upgradable semiconductor device assembly of claim 12, wherein ~~said~~ the mounting element-nonengagement state facilitates removal of ~~said~~ the at least one semiconductor device from ~~said~~ the at least one receptacle.

14. (Currently Amended) A semiconductor device package, comprising:  
at least one semiconductor device including a plurality of contact pads located proximate a single edge of ~~said at least one semiconductor device~~ thereof;  
a retainer including at least one receptacle configured to receive another edge of ~~said~~ the at least one semiconductor device; and  
at least one mounting element associated with ~~said~~ the retainer and configured to secure ~~said~~ the at least one semiconductor device to a carrier.

15. (Currently Amended) The semiconductor device package of claim 14, further comprising an alignment device configured to be mounted to the carrier ~~substrate~~.

16. (Currently Amended) The semiconductor device package of claim 15, wherein ~~said~~ the alignment device is configured to engage or to be engaged by ~~said~~ the at least one mounting element.

17. (Currently Amended) The semiconductor device package of claim 15, wherein ~~said~~ the alignment device includes an actuator positionable between a mounting element-engagement state and a mounting element-nonengagement state.

18. (Currently Amended) The semiconductor device package of claim 17, wherein ~~said~~ the mounting element-nonengagement state facilitates removal of ~~said~~ the at least one semiconductor device from ~~said~~ the alignment device.

19. (Currently Amended) The semiconductor device package of claim 15, wherein ~~said the~~ alignment device includes at least one receptacle configured to receive at least ~~said the~~ single edge of ~~said the~~ at least one semiconductor device.

20. (Currently Amended) The semiconductor device package of claim 19, wherein a plurality of contacts are positioned within ~~said the~~ at least one receptacle so as to facilitate electrical connection with corresponding contact pads of ~~said the~~ at least one semiconductor device.

21. (Currently Amended) The semiconductor device package of claim 14, wherein ~~said the~~ at least one semiconductor device comprises a semiconductor die and each of ~~said the~~ plurality of contact pads comprises a bond pad of ~~said the~~ semiconductor die.

22. (Currently Amended) The semiconductor device package of claim 14, wherein at least one contact pad of ~~said the~~ plurality of contact pads is disposed on ~~said the~~ single edge.

23. (Currently Amended) The semiconductor device package of claim 15, wherein ~~said the~~ alignment device includes a plurality of interconnection receptacles formed therein.

24. (Currently Amended) The semiconductor device package of claim 14, wherein ~~said the~~ at least one semiconductor device is secured within ~~said the at least one~~ receptacle of ~~said the~~ retainer with an adhesive material.